TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

PCN Number:	**20261116001.1**	**PCN Issued**	November 16, 2026
Qualify TIEM as an additional Assembly site for select devices		**Sample request deadline:**	January 15, 2027
		Estimated 1st ship date:	February 14, 2027
***Sample requests received after** January 15, 2027* **will not be supported.**			

Change type(s)
Assembly Site Packing/Shipping/Labeling

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of TI Melaka (TIEM) as an additional Assembly site for the list of devices shown below.

	Current site	Additional Site
Assembly site	TI CDAT	TIEM

- No material differences between sites

Qual details are provided in the Qual Data Section.

Reason for Change:	Continuity of supply.
Anticipated impact on Form, Fit, Function, Quality or Reliability:	None. Request the Supporting Data Packet for more details on the changes
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site Information

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TI CDAT	CDA	CHN	Chengdu
TIEM	CU6	MYS	Melaka

Sample product shipping label (not actual product label):



Products Affected:	
CC3300ENJARSBR	CC3350ENJARSBR
CC3301ENJARSBR	CC3351ENJARSBR

Qualification Report

Approve Date 11-MARCH -2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: MSPM0G3507SRGZR	QBS Package Reference: LM26LVQISD-130/NOPB	QBS Package, Process, Product Reference: M0G3507QPMRQ1	QBS Package Reference: TAS5825MRHBR	QBS Package Reference: TPS7A9401DSCR	QBS Package Reference: SN74AHC02BQAR
HAST	A2	Biased HAST	130C/85%RH	96 Hours		3/231/0	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	-	-	-	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	-	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	3/231/0	-	-	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	2/154/0	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	2/1600/0	-	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	3/228/0	-	-	-	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	3/228/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	-	-	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	-	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	-	-	-
FTY	E6	Final Test Yield	-	-	-	3/3/0	-	-	-	-

QBS: Qual By Similarity, also known as Generic Data
Qual Device MSPM0G3507SRGZR is qualified at MSL2 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2512-041

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and

assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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